

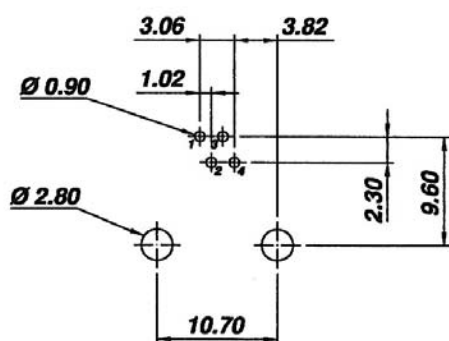
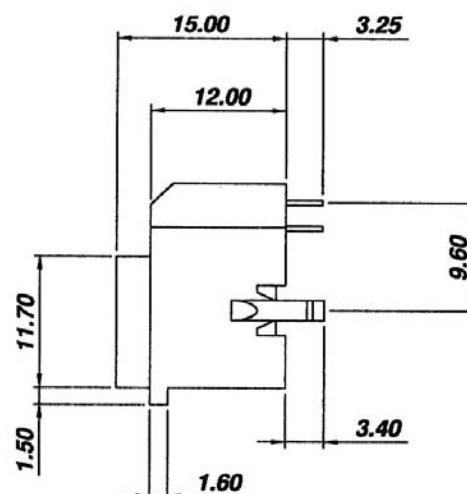
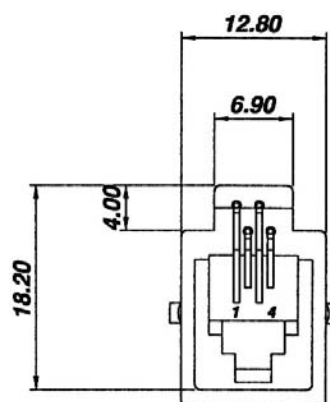
TOP ENTRY MODULAR PCB JACK 4P PROFILE=15.00MM (UNSHIELDED)

SPECIFICATIONS

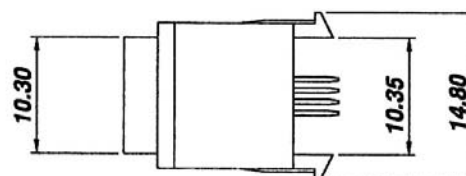
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
All materials must be RoHS compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N MJTJ - $\frac{44}{1} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"44" 4P4C
2. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

NOTE: P/N MJTJHT-44xB for High Temp. Version

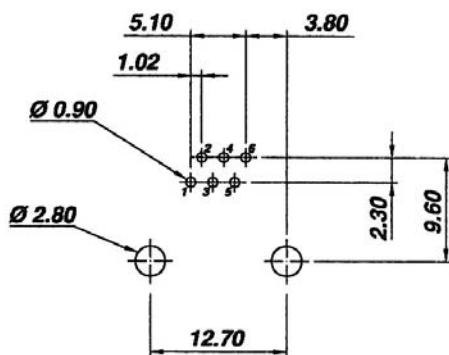
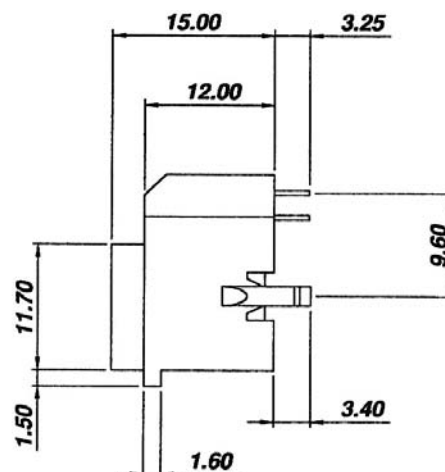
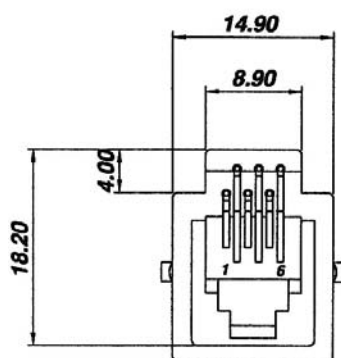
TOP ENTRY MODULAR PCB JACK 6P PROFILE=15.00MM (UNSHIELDED)

SPECIFICATIONS

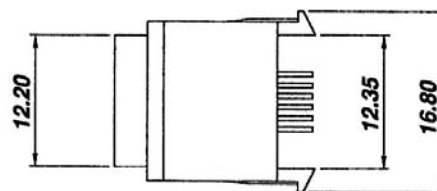
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Rating Voltage: 120V AC.
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MATERIALS

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Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
All materials must be RoHS compliant.



Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J T J - $\frac{x x x}{1 2}$ B

1. NO. OF POSITIONS & CONTACTS:

"66" 6P6C
"64" 6P4C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE: P/N MJTJHT-xxxB for High Temp. Version